
IRQSER DESERIALIZER

FEATURES

- 5-V Core Logic With PCI Interface
- Supports PCI Clock Frequencies up to 33 MHz
- Accepts IRQSER Serial Interrupt Stream Input From TI™ PC Card Controllers
- Provides System Access to All 15 ISA-Style IRQs and 4 PCI-Style Interrupts
- Offered in 48-Pin TQFP Package

DESCRIPTION

The PCI950 is an IRQSER interrupt deserializer that interfaces with existing and future TI PC Card controllers. The PCI950 accepts the IRQSER output of a TI PC Card controller and converts it to 16 ISA-style interrupts and 4 PCI-style interrupts. Interfacing the PC Card controller with the PCI950 permits system access of all available interrupts and features of the PC Card controller.

NOTE:

This product is for high-volume PC applications only. For a complete datasheet or more information contact support@ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| PCI950PT | ACTIVE | LQFP | PT | 48 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |
| PCI950PTG4 | ACTIVE | LQFP | PT | 48 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-3-260C-168 HR |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

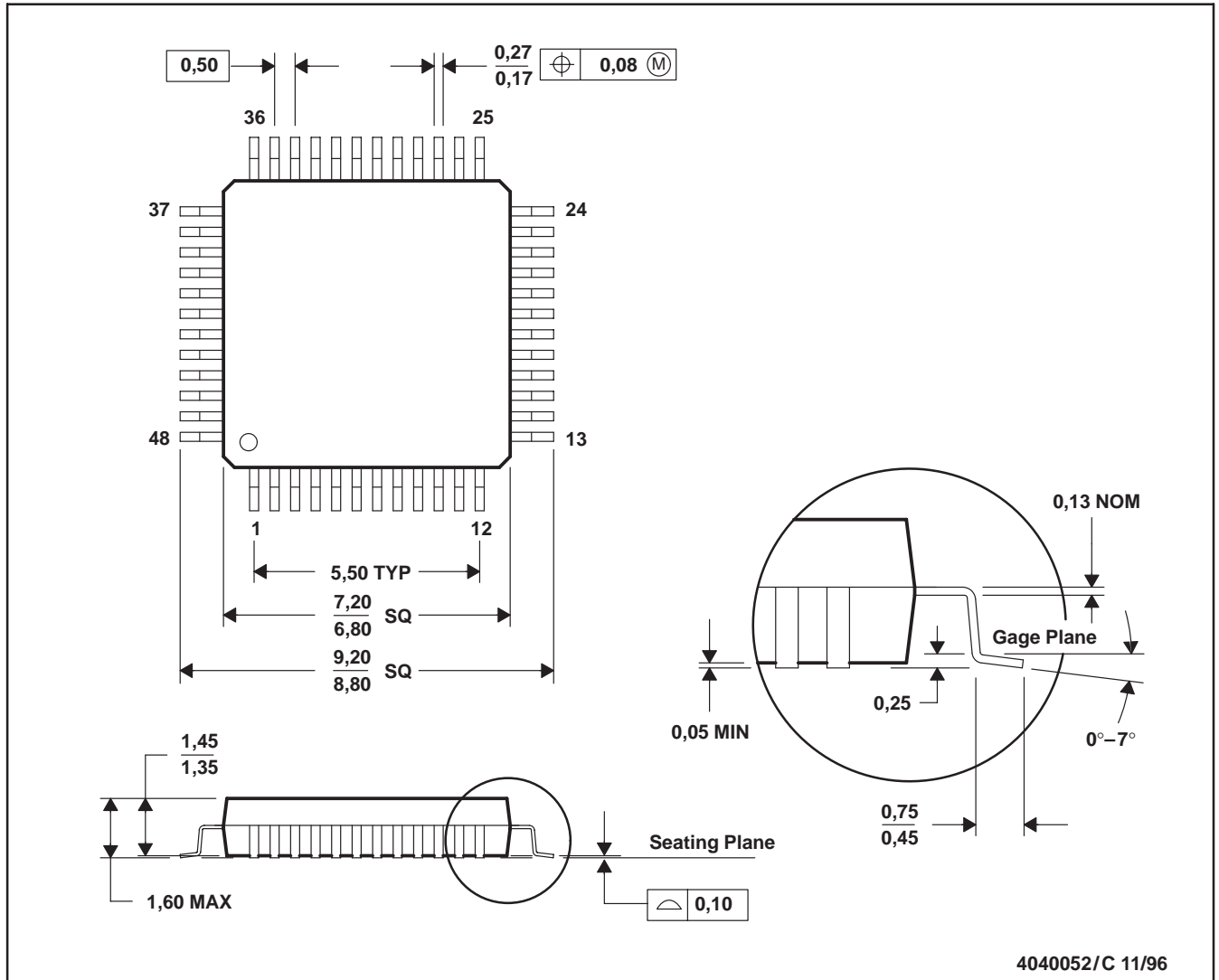
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PT (S-PQFP-G48)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026
 D. This may also be a thermally enhanced plastic package with leads connected to the die pads.

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